

Amendments

I. Amendments to the Claims

This listing of claims replaces all prior versions, and listings, of claims in the application:

1 (currently amended): A method for attaching a circuit element to a substrate, comprising:

 applying a conductive bonding material to a conductive portion of at least one of the circuit element and the substrate;

 positioning the circuit element in a desired location on the substrate;

 heating the conductive bonding material to promote one or more conductive bonds; and

 applying a non-conductive bonding material around only the edge of an area where the circuit element overlies the substrate to form a non-conductive bond between the circuit element and the substrate.

2 (original): The method of claim 1 wherein the conductive bonding material comprises a conductive epoxy resin.

3 (original): The method of claim 1 wherein the non-conductive bonding material comprises a liquid underfill encapsulant material.

4 (original): The method of claim 1 wherein the circuit element is one selected from the group consisting of a capacitor, a resistor, a diode, a transistor and an inductor.

5 (original): The method of claim 1 wherein heating the conductive bonding material comprises placing the substrate on a hot plate and heating the substrate to a temperature in a range of approximately 65°C to 85°.

6 (original): The method of claim 1 wherein the substrate comprises a laminate substrate and wherein the conductive bonding material comprises a conductive epoxy resin.

7 (original): The method of claim 1 wherein the substrate comprises a laminate substrate and wherein the conductive bonding material comprises a conductive solder.

8 (original): The method of claim 1 wherein the substrate comprises a laminate substrate and wherein the non-conductive bonding material comprises a flip chip underfill material.

9 (currently amended): A method of attaching an electrical device to a circuit board, comprising:

applying a conductive adhesive to electrical conductors of at least one of the electrical device and the circuit board;

positioning the electrical device relative to the circuit board so that corresponding electrical conductors are aligned and in contact;

seating the electrical device in the conductive adhesive;

gel curing the conductive adhesive at an elevated temperature;

applying an amount of liquid encapsulant material around only the edge of an area where the electrical device overlies the circuit board ~~edges of the electrical device near the circuit board~~; and

full curing the conductive adhesive and the encapsulant material.

10 (original): The method of claim 9 wherein the electrical device is one selected from the group consisting of a resistor, a capacitor, a diode, a transistor and an inductor.

11 (original): The method of claim 9 wherein the liquid encapsulant material comprises a flip chip underfill material.

12 (original): The method of claim 9 wherein the conductive adhesive comprises a silver epoxy resin.

13 (original): The method of claim 9 wherein the conductive adhesive comprises a gold epoxy resin.

14 (original): The method of claim 9 wherein the circuit board comprises a laminate substrate.

15-17 (cancelled).